

Silicon N-Channel Planar Power MOSFET

Description

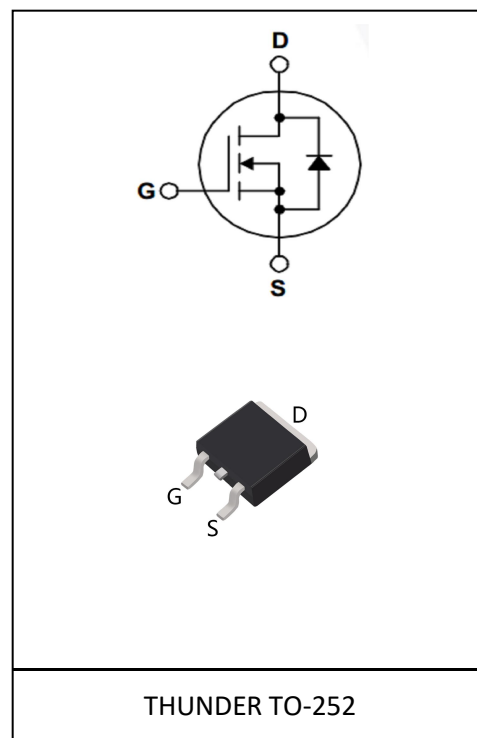
The TH3N80PG utilizes the latest processing techniques to achieve low on-resistance per silicon area. Additional features of this MOSFET are 150°C operating junction temperature and high repetitive peak current capability. These features combine to make this MOSFET a highly efficient, robust and reliable device for PDP driving applications. It can be used in a wide variety of applications.

General Features

- $V_{DS}=800V, I_D=3A$
- Low ON Resistance, $R_{DS(ON)}=3.8\Omega @ V_{GS}=10V, I_D=1.5A$
- Low reverse transfer capacitance
- Low Qg for fast response
- Short fall & rise times for fast switching
- 100% single pulse avalanche energy Test

Application

- Power switching application
- Digital amplifier
- Adapter and charger



Product Summary

V_{DS}	800V
$R_{DS(on)}$	3.8Ω
I_D	3A

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	800	V
Continuous drain current $T_C = 25^\circ C$ (Silicon limit)	I_D	3	A
Pulsed drain current ($T_C = 25^\circ C$, t_p limited by T_{jmax})	I_{DM}	12	A
Avalanche energy, single pulse ($L=10mH$, $R_g=25\Omega$)	E_{AS}	120	mJ
Gate-Source voltage	V_{GS}	±30	V
Power dissipation ($T_C = 25^\circ C$)	P_D	104	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+150	°C

Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	R_{thJC}	1.2	°C/W
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	100	

Electrical Characteristic (at $T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	800	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{GS(th)}$	2.5	-	4.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=800V, V_{GS}=0V$ $T_j=25^{\circ}\text{C}$
		-	-	10	μA	$V_{DS}=640V, V_{GS}=0V$ $T_j=125^{\circ}\text{C}$
Gate-source leakage current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 30V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	3.8	4.8	Ω	$V_{GS}=10V, I_D=1.5A$

Dynamic Characteristic

Input Capacitance	C_{iss}	-	575	-	pF	$V_{GS}=0V, V_{DS}=25V,$ $f=1\text{MHz}$
Output Capacitance	C_{oss}	-	54	-		
Reverse Transfer Capacitance	C_{rss}	-	7.9	-		
Gate Total Charge	Q_g	-	15	-	nC	$V_{GS}=10V, V_{DS}=640V,$ $I_D=3A$
Gate-Source charge	Q_{gs}	-	2.5	-		
Gate-Drain charge	Q_{gd}	-	6	-		
Turn-on delay time	$t_{d(on)}$	-	9	-	ns	$V_{DD}=400V, I_D=3A,$ $R_G=25\Omega$
Rise time	t_r	-	9	-		
Turn-off delay time	$t_{d(off)}$	-	32	-		
Fall time	t_f	-	14	-		
Gate resistance	R_G	-	1.4	-	Ω	$V_{GS}=0V, V_{DS}=0V,$ $f=1\text{MHz}$

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	-	1.5	V	$V_{GS}=0V, I_{DS}=3A$
Body Diode Continuous Forward Current	I_S	-	-	3	A	$T_C=25^{\circ}C$
Body Diode Reverse Recovery Time	t_{rr}	-	140	-	ns	$T_C=25^{\circ}C, I_S=3A, di/dt=100A/us$
Body Diode Reverse Recovery Charge	Q_{rr}	-	450	-	μC	

Typical Performance Characteristics

Fig 1: Output Characteristics

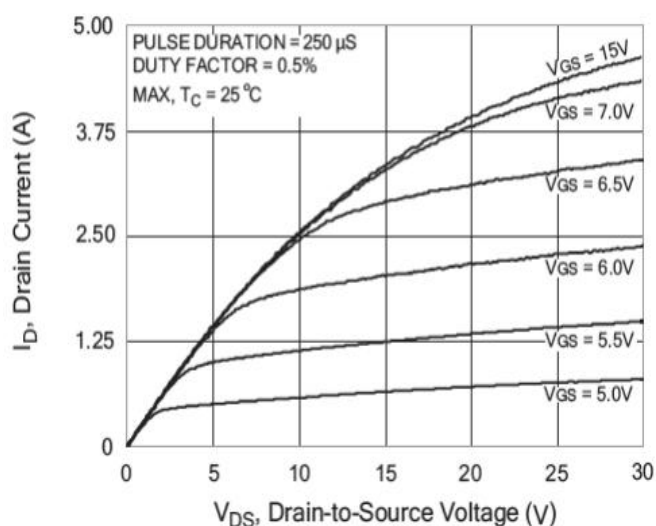


Fig 2: Transfer Characteristics

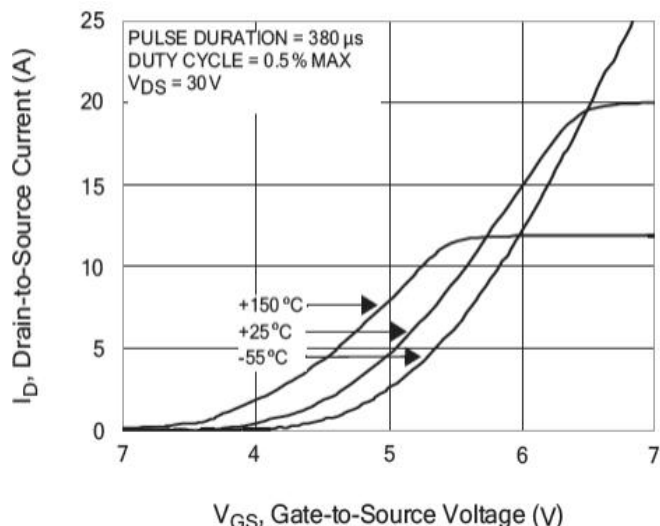


Fig 3: $R_{DS(on)}$ vs. Temperature

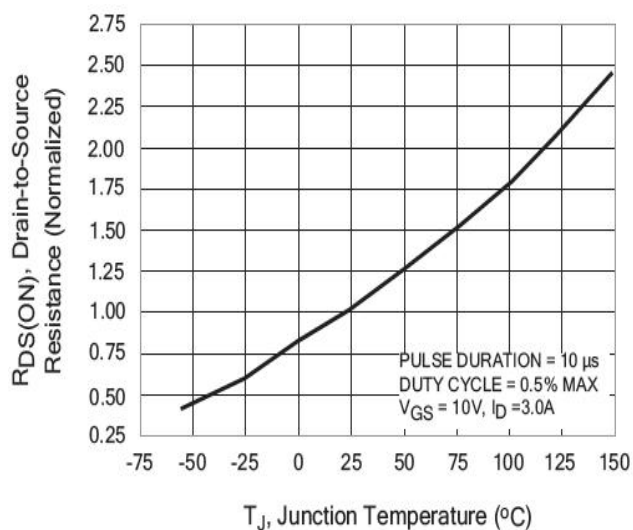


Fig 4: Body-diode Forward Characteristics

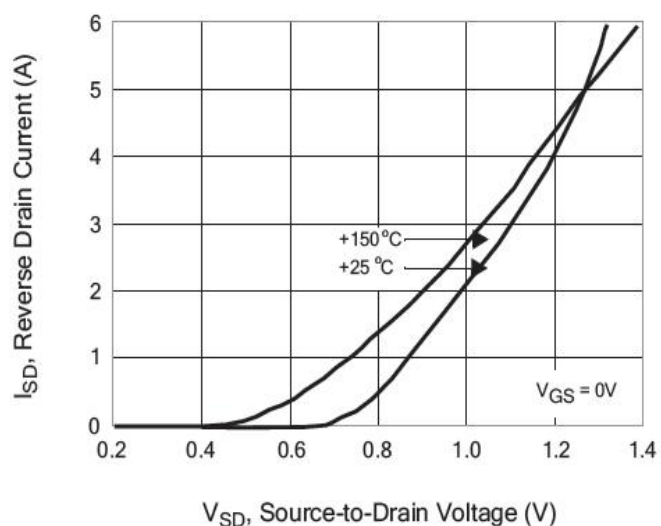


Fig 5: Power Dissipation

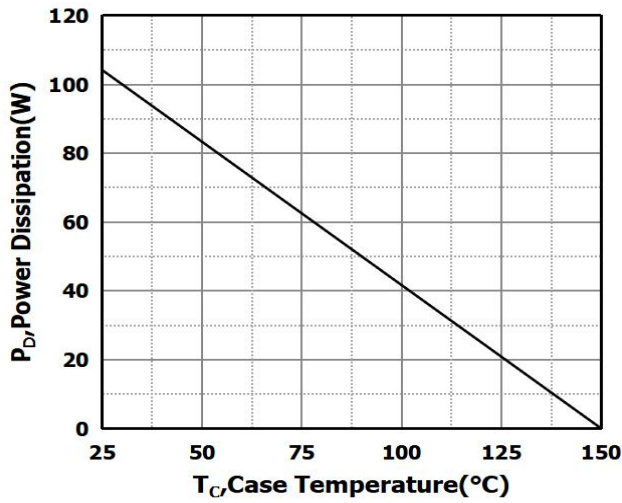


Fig 6: Drain Current Derating

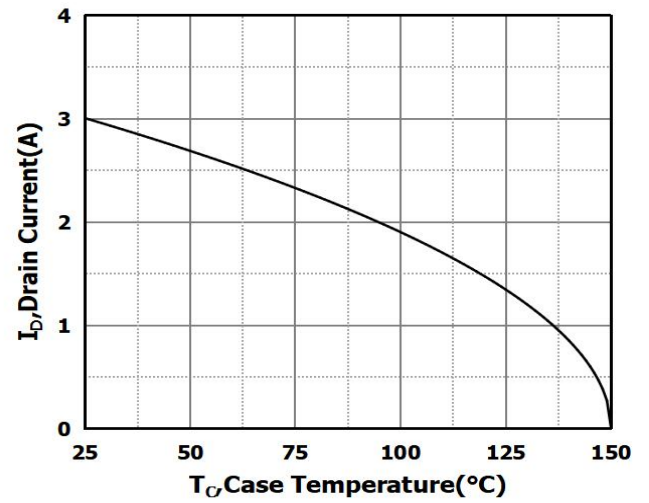


Fig 7: Capacitance Characteristics

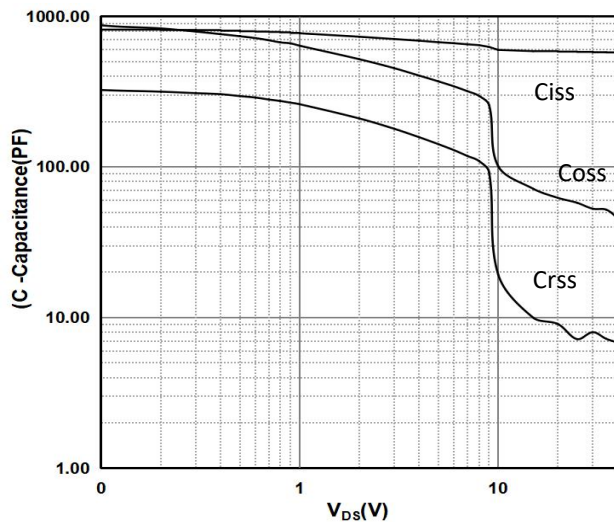


Fig 8: Safe Operating Area

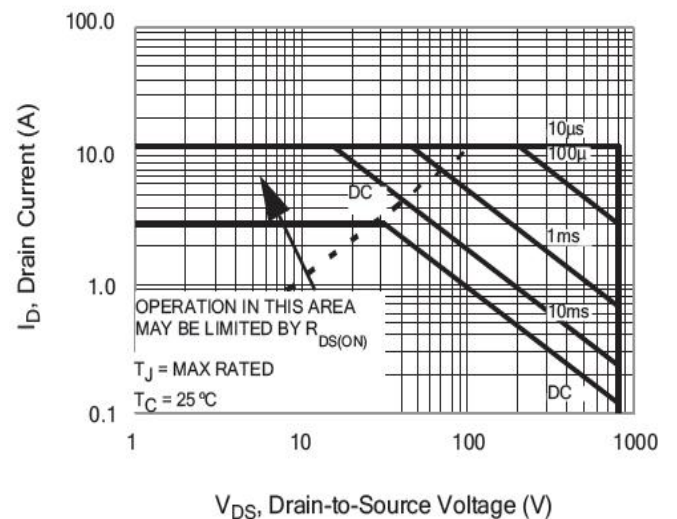
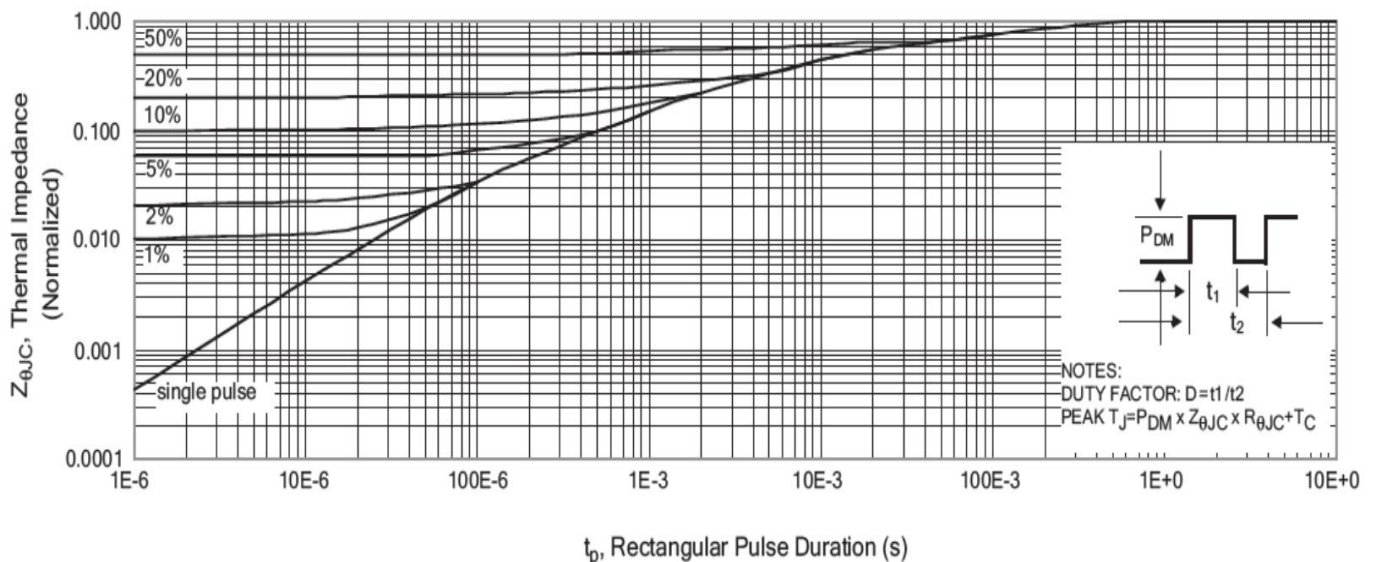
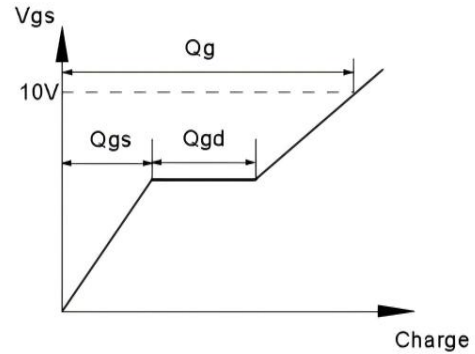
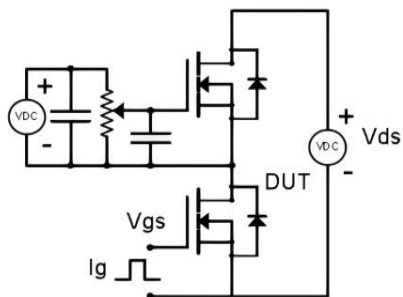


Fig 9: Maximum Effective Transient Thermal Impedance, Junction-to-Case

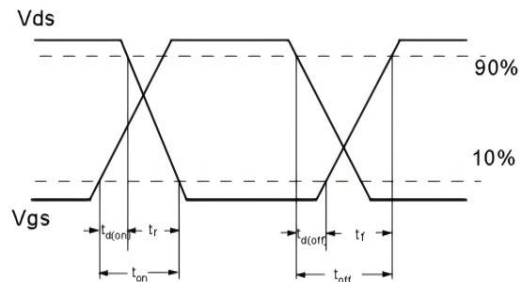
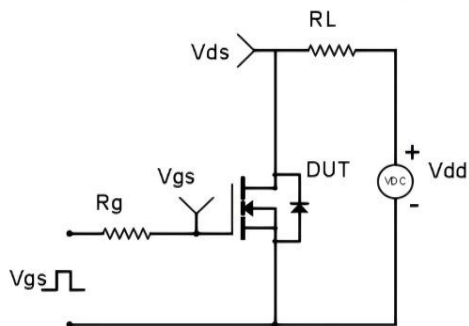


Test Circuit & Waveform

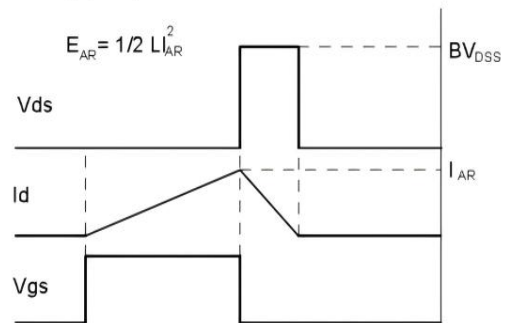
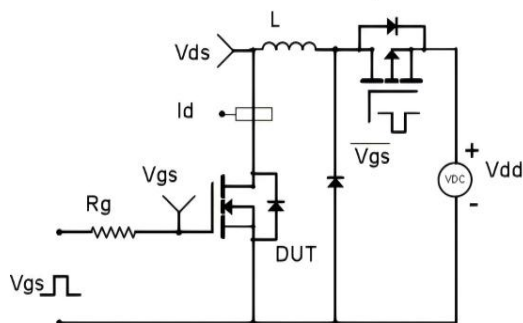
Gate Charge Test Circuit & Waveform



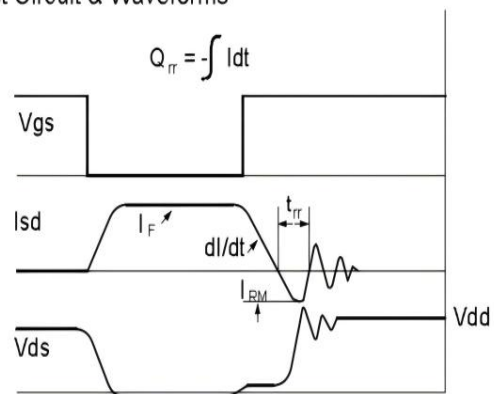
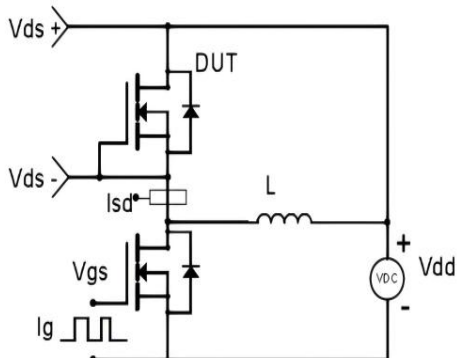
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



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